



Material Content Data Sheet



Sales Product Name		BSB013NE2LXI		Issued		29. August 2013			
MA#		MA000961732							
Package		MG-WDSO-N-2-8		Weight*		83.36 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.882	4.66	4.66	46575	46575	
leadframe	non noble metal	copper	7440-50-8	74.415	89.29	89.29	892738	892738	
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2534		
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10077	12611	
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2534	2534	
glue	plastics	epoxy resin	-	0.178	0.21		2139		
	noble metal	silver	7440-22-4	1.095	1.31	1.52	13138	15277	
solder	non noble metal	copper	7440-50-8	0.011	0.01		132		
	noble metal	silver	7440-22-4	0.066	0.08		790		
	non noble metal	tin	7440-31-5	2.119	2.54	2.63	25416	26338	
passivation	plastics	epoxy resin	-	0.327	0.39	0.39	3927	3927	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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